

AMENDMENTS TO THE CLAIMS

The current status of all claims in the Application is as follows:

1. (CURRENTLY AMENDED) A coil bobbin comprising:

a housing having an interior and including a floor with at least one electrical lead-in projecting through an aperture in said floor for attachment to a printed circuit board, said at least one electrical lead-in having a given diameter and being provided with thermal-strain relief positioned within said interior, said aperture in said floor having a diameter larger than said given diameter.

2. (ORIGINAL) The coil bobbin of Claim 1 wherein said thermal-strain relief comprises a loop.

3. (CURRENTLY AMENDED) The coil bobbin of Claim 2 wherein said housing includes a wall adjacent said thermal-strain relief and said wall has a free-play zone therein **comprising a detent** into which said loop extends.